



华润微电子(重庆)有限公司

CRTD110N03L

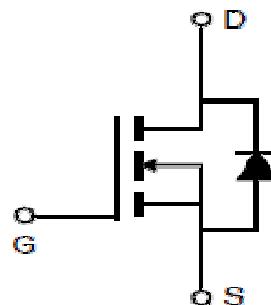
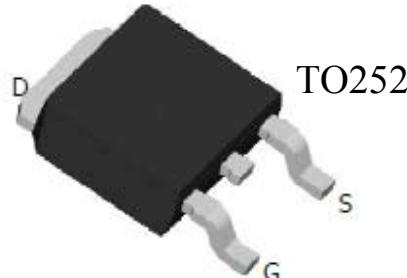
## Features

- Lead free and Green Device Available
- Low R<sub>ds-on</sub> to Minimize Conductive Loss
- High avalanche Current

<b>V<sub>DSS</sub></b>	<b>30V</b>
<b>R<sub>ds(on)</sub> V<sub>gs</sub>=10V typ.</b>	<b>9mΩ</b>
	<b>max. 11mΩ</b>
<b>R<sub>ds(on)</sub> V<sub>gs</sub>=4.5V typ.</b>	<b>11mΩ</b>
	<b>max. 13mΩ</b>
<b>I<sub>D</sub> @ V<sub>gs</sub>=10V (Silicon limited)</b>	<b>45A</b>
<b>I<sub>D</sub> (Package limited)</b>	<b>20A</b>

## Application

- Power Tool
- Boost Converters for LED Lighting
- SMPS



## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Param	Maximum	Unit
$V_{DSS}$	Drain-to-Source Voltage	30	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$ $V_{gs}=10\text{V}$	$T_c=25^\circ\text{C}$ (Silicon limited)	45	A
	$T_c=100^\circ\text{C}$ (Silicon limited)	32	
	$T_c=25^\circ\text{C}$ (Package limited)	20	
	$T_c=25^\circ\text{C}$ (Silicon limited)	41	
	$T_c=100^\circ\text{C}$ (Silicon limited)	29	
	$T_c=25^\circ\text{C}$ (Package limited)	20	
$I_{DP}$	Pulsed Drain Current $T_c=25^\circ\text{C}$	-	A
$I_{AS}$	Avalanche Current ( $L=0.3\text{mH}$ )	11	A
$E_{AS}$	Avalanche Energy ( $L=0.3\text{mH}$ )	18	mJ
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	W
		$T_c=100^\circ\text{C}$	
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55~175	°C

## Thermal Characteristics

Symbol	Parameter	Max.	Unit
$R_{thJC}$	Thermal resistance, junction to case	3.7	°C/W
$R_{thJA}$	Thermal resistance, junction to ambient	86	°C/W



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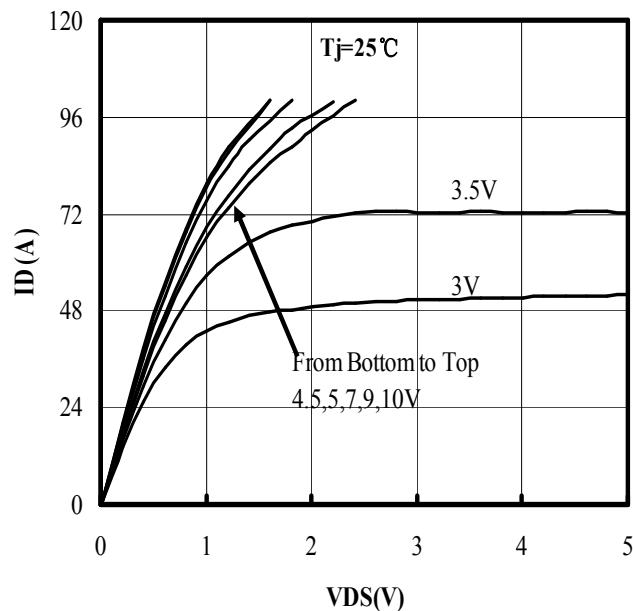
CRTD110N03L

**Electrical Characteristics (TA=25°C unless otherwise noted)**

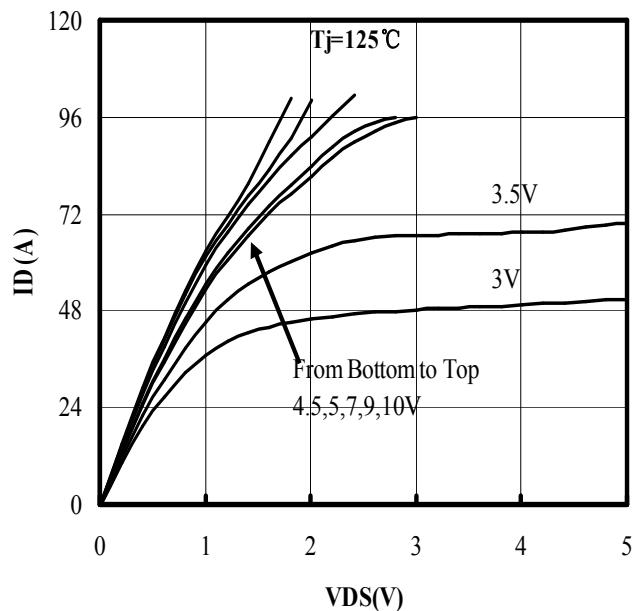
Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Unit
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	—	—	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	—	—	1	uA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.8	—	1.8	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	—	—	±100	nA
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =12A	—	9	11	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	—	11	13	
G <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =12A	—	43	—	S
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>SD</sub> =25A, V <sub>GS</sub> =0V	—	0.8	1.3	V
I <sub>s</sub>	Diode Continuous Forward Current		—	—	20	A
t <sub>rr</sub>	Reverse Recovery Time	IS=12A, di/dt=100A/us	—	13	—	nS
Q <sub>rr</sub>	Reverse Recovery Charge		—	1.6	—	nC
<b>Dynamic Characteristics</b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, Frequency=1MHz	—	2.5	—	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, F=1MHz	—	1250	—	pF
C <sub>oss</sub>	Output Capacitance		—	168	—	
C <sub>rss</sub>	Reverse Transfer Capacitance		—	127	—	
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> =15V, ID=1A, R <sub>g</sub> =3 Ω, V <sub>GS</sub> =4.5V	—	15	—	nS
t <sub>r</sub>	Rise Time		—	25	—	
t <sub>d(off)</sub>	Turn-Off Delay Time		—	39	—	
t <sub>f</sub>	Fall Time		—	22	—	
<b>Gate Charge Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =25V, V <sub>GS</sub> =10V, ID=14A	—	23	—	nC
Q <sub>gs</sub>	Gate-to-Source Charge		—	2.2	—	
Q <sub>gd</sub>	Gate-to-Drain Charge		—	5.5	—	

## Typical Operating Characteristics

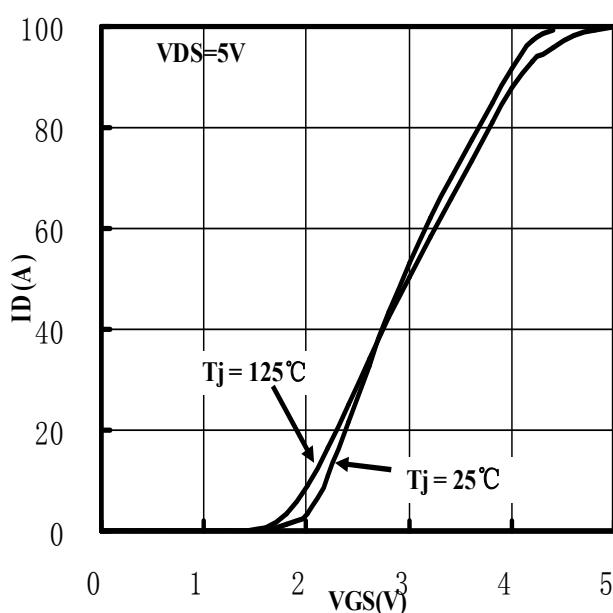
**Figure 1. Typ. Output Characteristics**



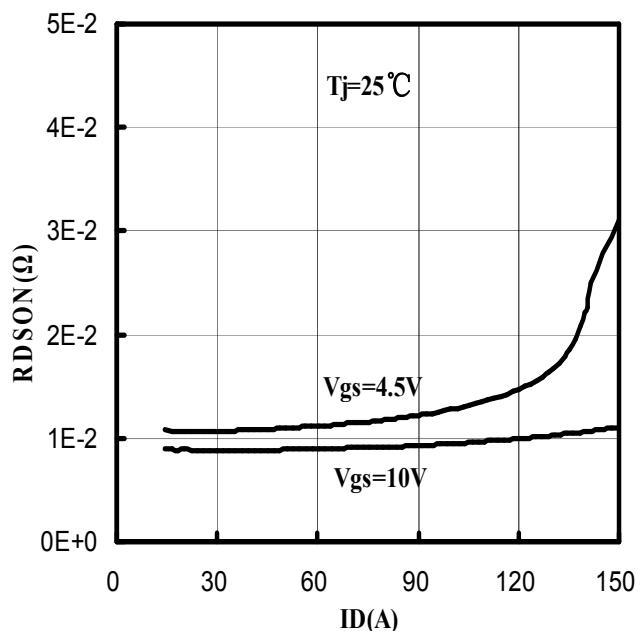
**Figure 2. Typ. Output Characteristics**



**Figure 3. Transfer Characteristics**

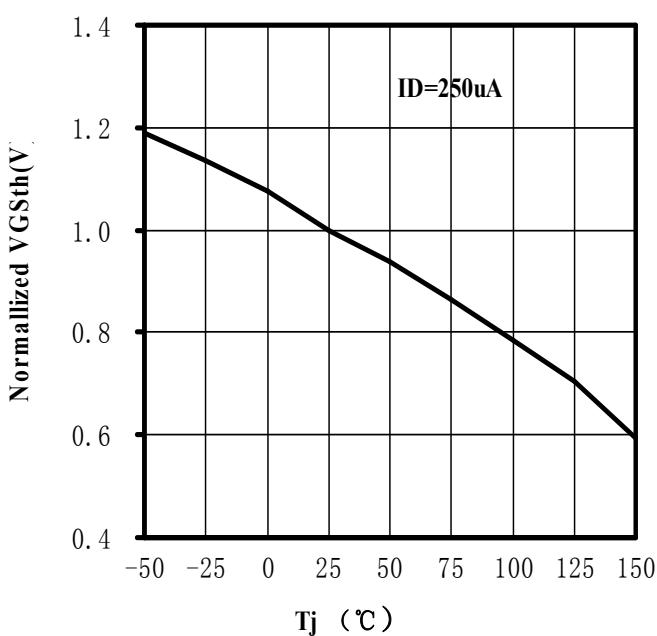


**Figure 4.  $R_{DSON}$  vs. Drain Current Characteristics**

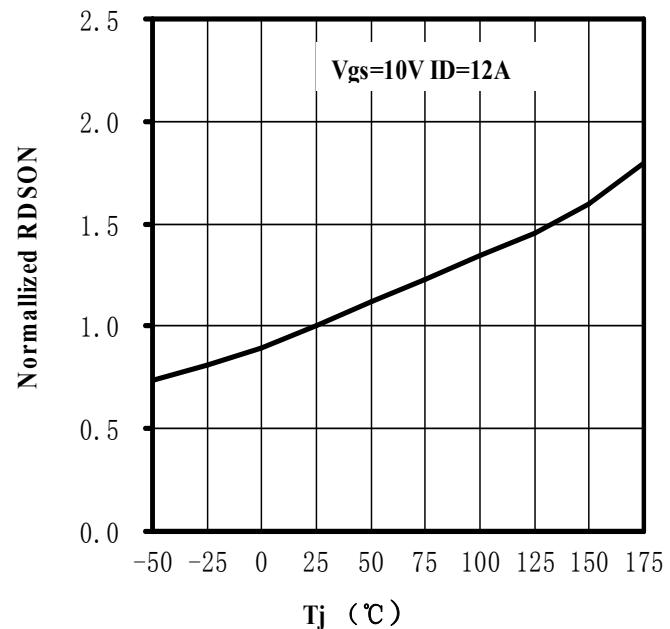


## Typical Operating Characteristics

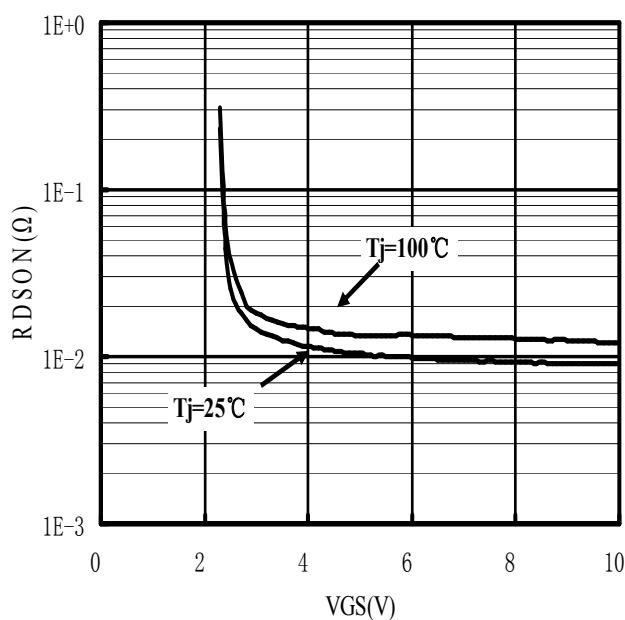
**Figure 5. Gate Threshold Voltage Characteristics**



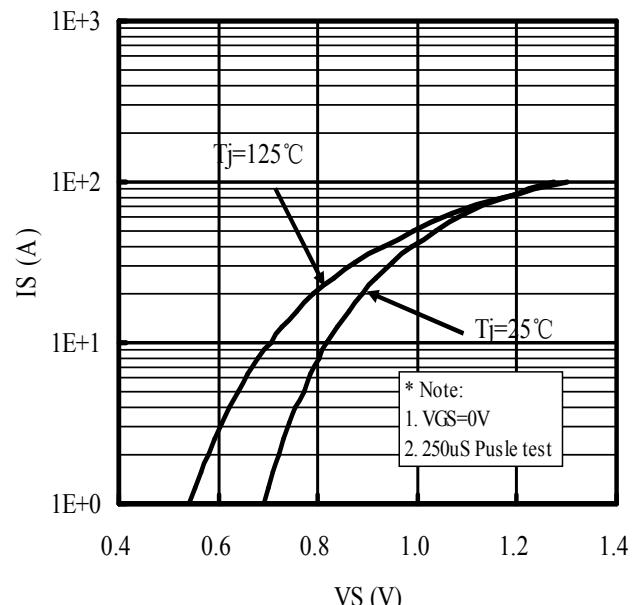
**Figure 6. Rdson vs. Junction Tem Characteristics**



**Figure 7. Rdson vs. VGS Characteristics**

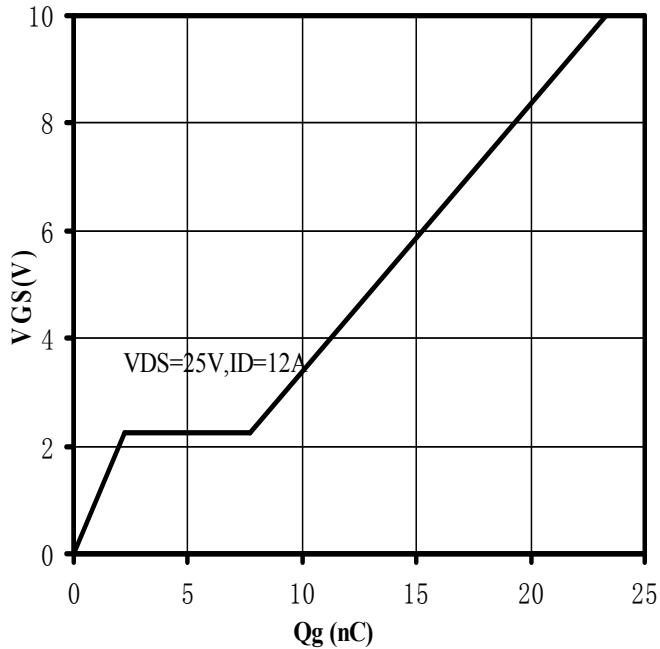


**Figure 8. IS vs. VSD Characteristics**

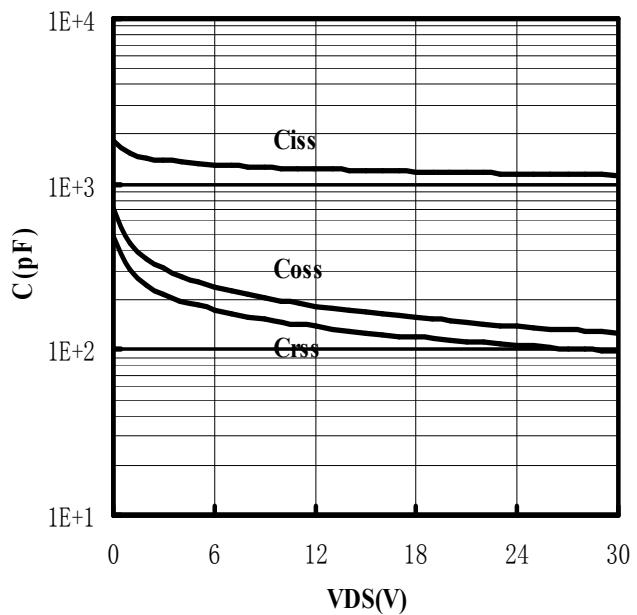


## Typical Operating Characteristics

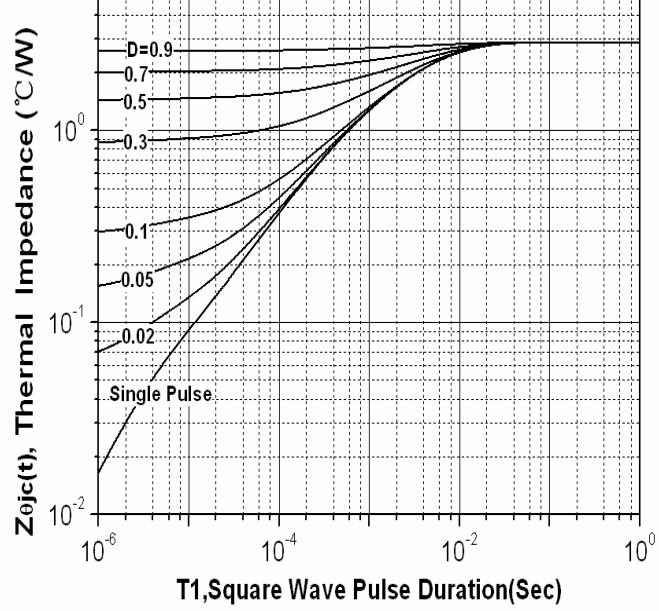
**Figure 9. Gate Charge Characteristics**



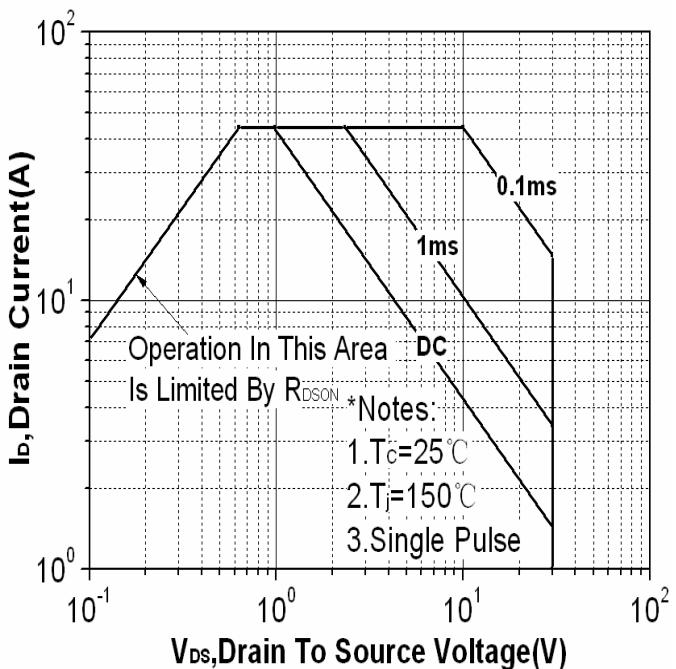
**Figure 10. Capacitance Characteristics**



**Figure 11. Thermal Resistance Characteristics**



**Figure 12. SOA**

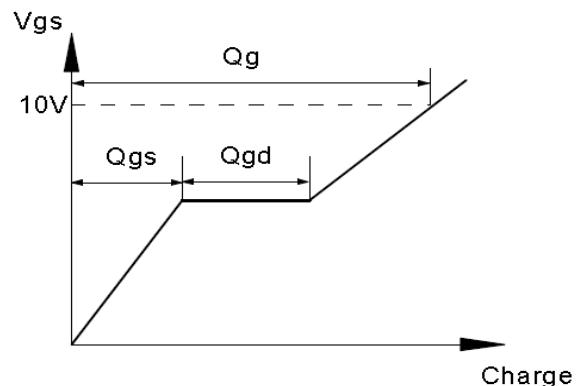
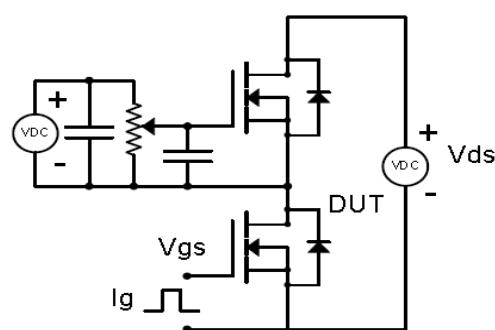


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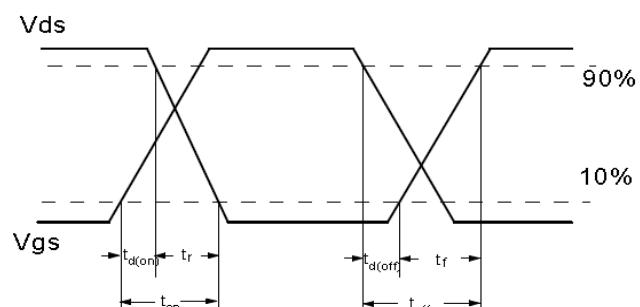
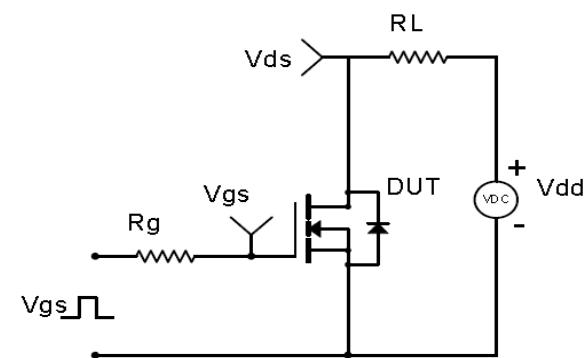


## Test Circuit & Waveform

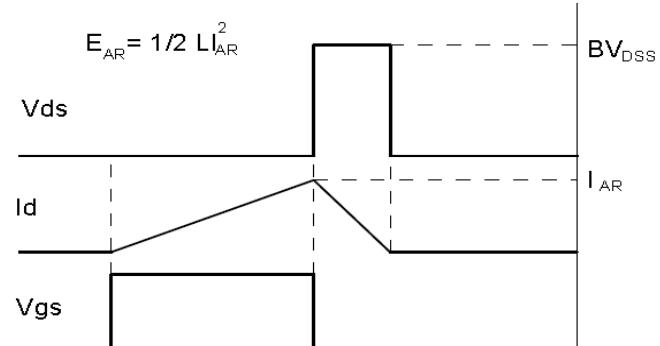
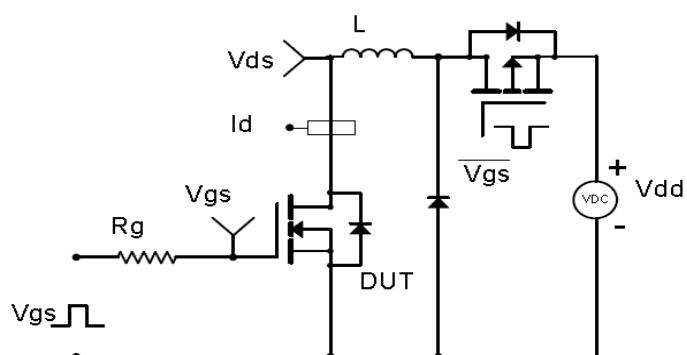
Gate Charge Test Circuit &amp; Waveform



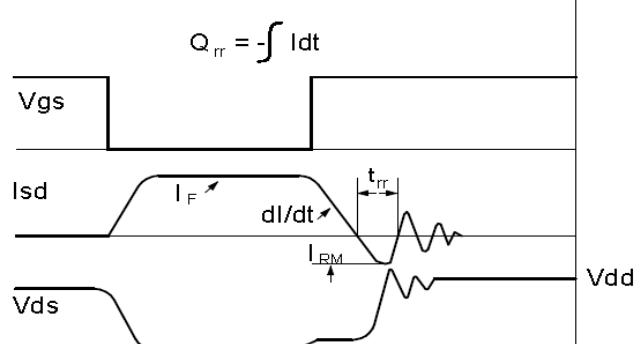
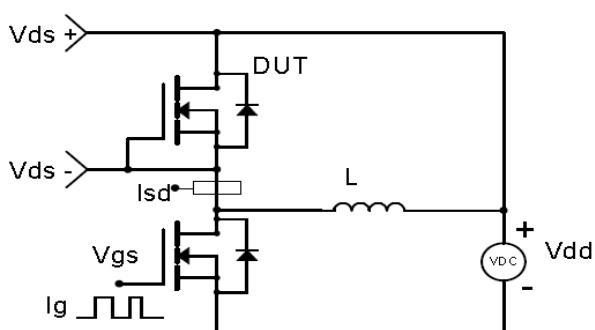
Resistive Switching Test Circuit &amp; Waveforms



Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms

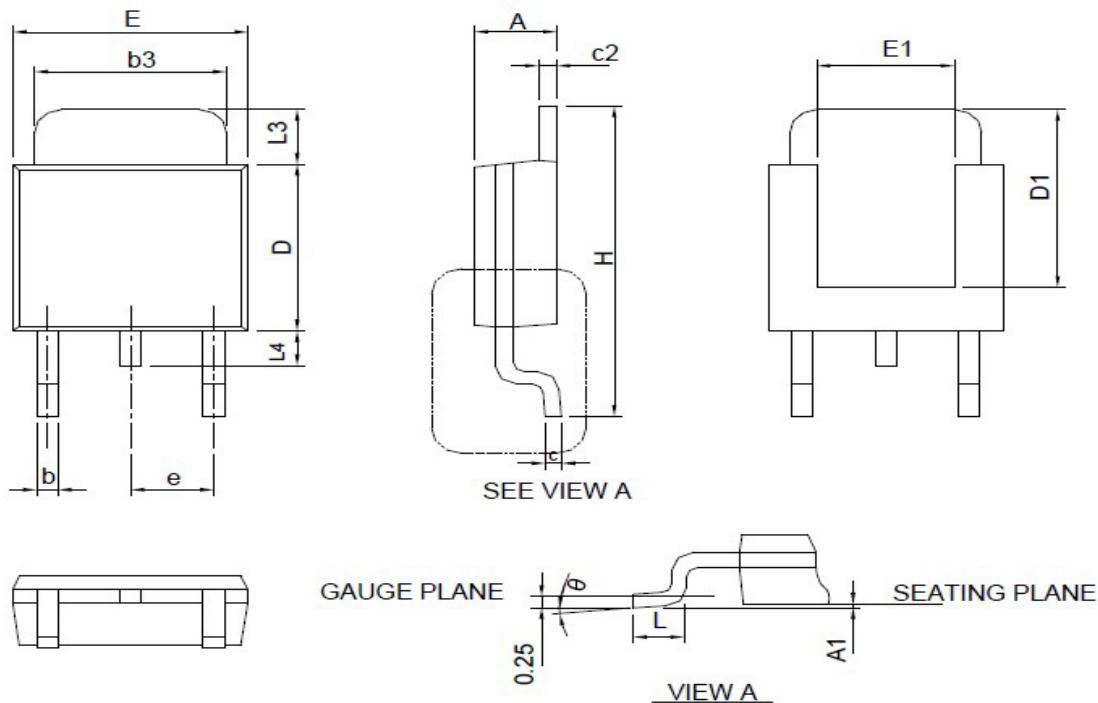


Diode Recovery Test Circuit &amp; Waveforms



## Package Information

TO-252-3



SYMBOL	TO-252-3			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
θ	0°	8°	0°	8°

Note : Follow JEDEC TO-252 .